TE Internal #: 1871058-2

Board-to-Board, 64 Position, 1 mm [.039 in] Centerline, Vertical, Black, 11 mm [.433 in] Height, 8.88 mm [.35 in] Width, PCI & PCI

**Express Connectors** 

View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 64
PCI Generation: 2 & 3

Centerline (Pitch): 1 mm [.039 in]

Termination Post & Tail Length: 2 mm [.079 in]

PCB Contact Termination Area Plating Material Thickness

Contact Mating Area Plating Material

PCB Contact Termination Area Plating Material

Contact Base Material

### **Features**

#### **Product Type Features**

Printed Circuit Board
Board-to-Board
2
64
Vertical
Without
50 VAC
2.863 g
Black
1.1 A

.5 µm

Tin

Gold (Au)

Copper Alloy



PCB Contact Termination Area Plating Material Finish	Matte
	30 μin
Termination Features	
Termination Method to PCB	Through Hole - Press-Fit
Termination Post & Tail Length	2 mm[.079 in]
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	1 mm[.039 in]
Dimensions	
PCB Thickness (Recommended)	1.6 mm[.063 in]
PCB Thickness (Accepted)	1.57 mm[.062 in]
Connector Length	39 mm[1.535 in]
Connector Height	11 mm[.433 in]
Connector Width	8.88 mm[.35 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Bus Type	PCI Express
PCI Generation	2 & 3
Packaging Features	
Packaging Method	Box & Tray, Tray
Packaging Quantity	40

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold



EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**



# Customers Also Bought











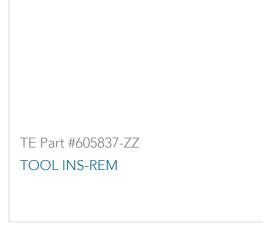


TE Part #ZPF00000000003594 724-0001-22











#### **Documents**

### **Product Drawings**

PCI EXPRESS CONN. EON TYPE, 64P, L=2.0

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1871058-2\_E.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1871058-2\_E.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1871058-2\_E.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

## **Product Specifications**

**Product Specification** 

Japanese

**Product Specification** 

English